

XPose!

The best computer-to-plate system available:
Thermo plates, laser diodes, and inside drum
in one flexible system



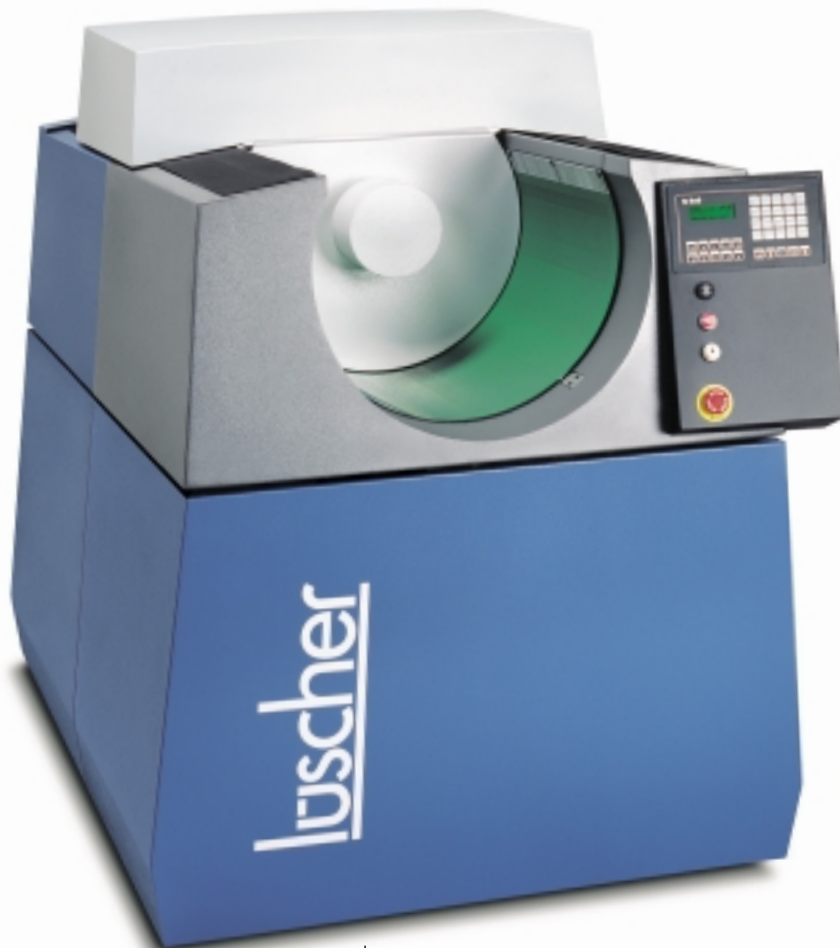
Lüscher XPose! The innovations



For the first time this unique Lüscher design combines inside and outside drum technologies (patents have been applied for). The thermal computer-to-plate transfer of pictures inside the LüscherXpose! can take place in a normally lit room. Thermal exposure means best quality reproduction, a very high number of copies, resistance against UV inks, and constant plate quality. Long-lived laser diodes used for thermal imaging contribute to the excellent cost/benefit ratio.

The inside drum of the XPose! enables you to expose any size of plate. No complicated mechanism is needed for drum rotation or plate mounting. Thanks to the simplified inside drum, the space requirement of the system as a whole has been reduced.

The Lüscher XPose! is the first and only CTP exposer to combine thermal CTP, laser diodes, and inside drum in one CTP system. An automatic plate handling device may be added if and when required. The Lüscher XPose! actually progresses along with digital plate production and enables you to catch up with the latest CTP technology with minimum risk for your investment.



| XPose! 130

Lüscher XPose! The benefits



The Lüscher XPose! brings numerous advantages to print plate production:

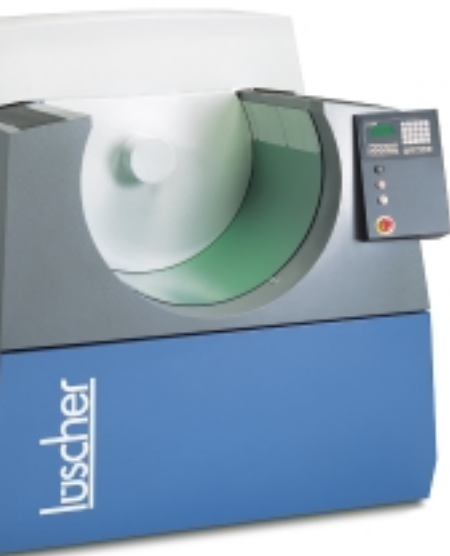
Set-up time is reduced by several minutes for each print job (time savings of 20 % are normal);

Start-up waste is reduced by 30 - 70 %;

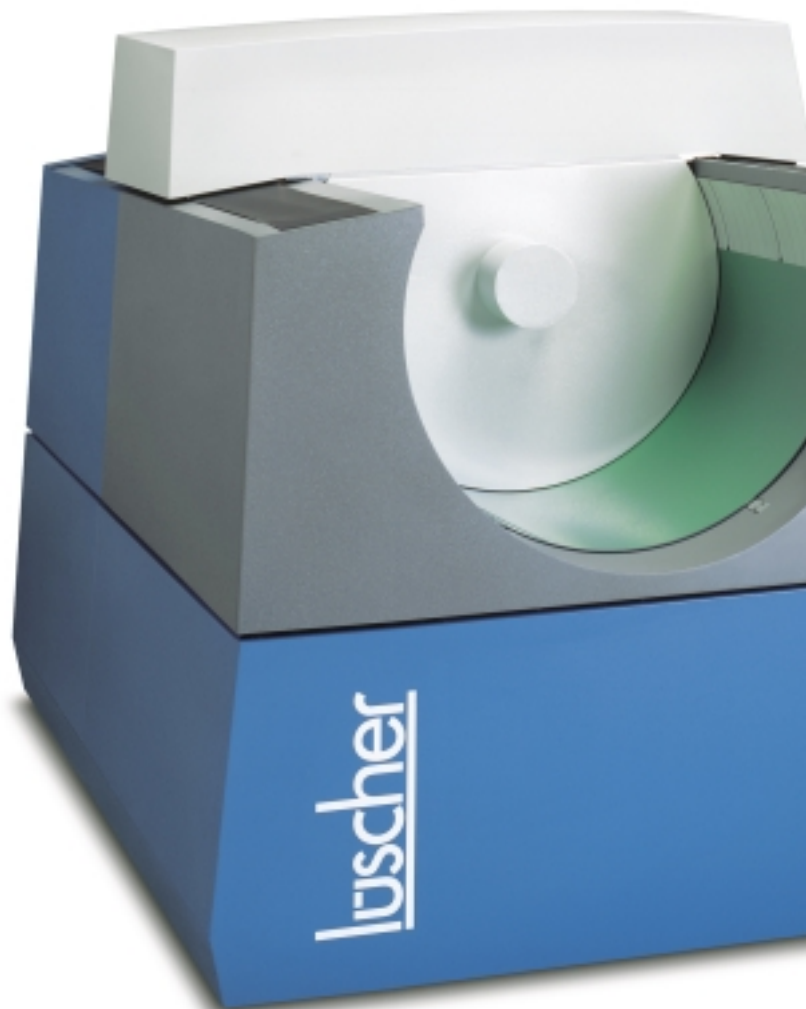
Print quality is improved due to automatic register adjustment;

Higher reproduction quality is achieved as the dot stays on the plate from 1 - 99 %.

The benefits from these advantages are a higher printing press utilization, better product quality, lower costs, and considerably shorter production times.



| XPose! 160



| XPose! 180

Lüscher XPose! The laser diodes

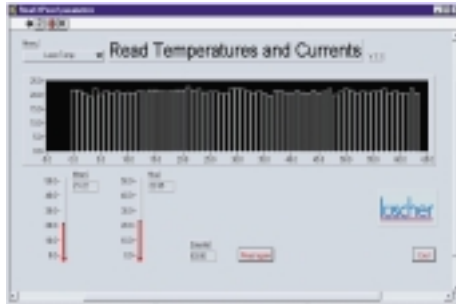


The laser diodes are supervised and readjusted as necessary during exposure by the Lüscher diagnostic system. Should a diode fail, the system will continue to function at a slightly reduced speed while the diode is exchanged. Production does not have to be interrupted. The Lüscher diode drum has made expensive optics and water cooling redundant. The slogan „more simplicity for more reliability“ that guided its development has come true.

Laser diodes are subject to ongoing development. This is to the XPose! user's benefit because diodes are easily replaced without readjustment. This also applies in case a diode fails.



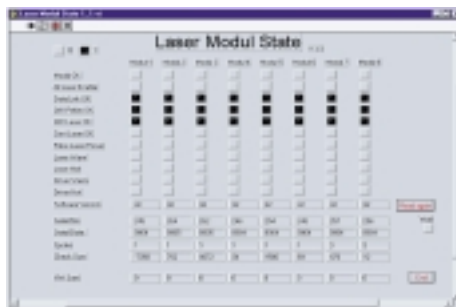
Lüscher XPose! On-line service



Remote maintenance of your system is available. Our service engineers can locate and correct defects on-line – no waiting and no travelling expenses occur.

We also offer preventive maintenance and check-up of your XPose!. This simple and inexpensive precaution helps to avoid breakdowns during production. The Lüscher engineers can even reset and configure your RIP remotely.

Of course you also get personal user service and production support on site whenever needed. Lüscher's service support program makes sure your XPose! works perfectly well.



XPose! PHS – fully automatic CTP

This unique Lüscher machine automates the plate loading and unloading procedure. It gives simultaneous access to four different plate sizes (with six sizes as an option). 100 plates can be stacked per magazine. Single plates of differing sizes can be manually loaded at any time.



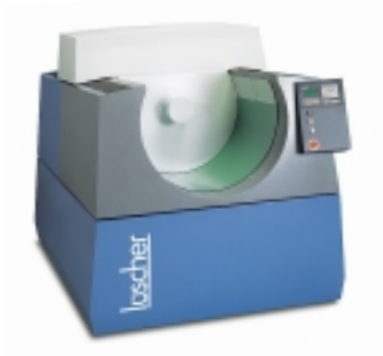
| XPose! DPHS – dual plate handling system

Lüscher XPose!

Technical data

	XPose! 75	XPose! 130	XPose! 160	XPose! 180
Maximum plate size	760 x 650 mm	1130 x 950 mm	1700 x 1370 mm	2030 x 1485 mm
Maximum exposure area	760 x 650 mm	1130 x 950 mm	1700 x 1370 mm	2030 x 1485 mm
Minimum plate size	380 x 250 mm	500 x 360 mm	500 x 400 mm	650 x 550 mm
Minimum exposure area	unrestricted	unrestricted	unrestricted	unrestricted
Plate thickness	0.15-0.3 mm	0.15-0.4 mm	0.15-0.5 mm	0.15-0.5 mm
Automatic focus	acc. to plate thickness	acc. to plate thickness	acc. to plate thickness	acc. to plate thickness
Exposure head	32 x 830 nm diodes, 1W	64 x 830 nm diodes, 1W	64 x 830 nm diodes, 1W	64 x 830 nm diodes, 1W
Resolution	2400 dpi	2400 dpi	2400 dpi	2400 dpi
Smallest dot size	10 microns	10 microns	10 microns	10 microns
Data transfer to XPose!	LVD-SCSI			
Imaging speed (depends on make of plate)	135 mm/minute	270 mm/minute	205 mm/minute	162 mm/minute
Repeatability	0.01 mm	0.01 mm	0.01 mm	0.01 mm
Dimensions (lxwxh)	2406 x 1149 x 1495 mm	2650 x 1200 x 1550 mm	3000 x 1495 x 1650 mm	3050 x 1710 x 1890 mm
Weight	≈ 900 kg	≈ 1000 kg	≈ 1400 kg	≈ 1650 kg
Approvals	TÜV, CE, DIN			
Power supply	3 x 400 V, 50 Hz + N + PE 16 A			
Environment conditions	50-65% relative humidity at 18-25°C			

We reserve the right to change design or technical data without notice.



Options

PHS/DPHS – plate handling system/dual plate handling system
 FM screening
 2540 dpi
 1800 dpi
 1270 dpi
 1200 dpi
 XPose! 75: 64 x 830 nm diodes

lüscher

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